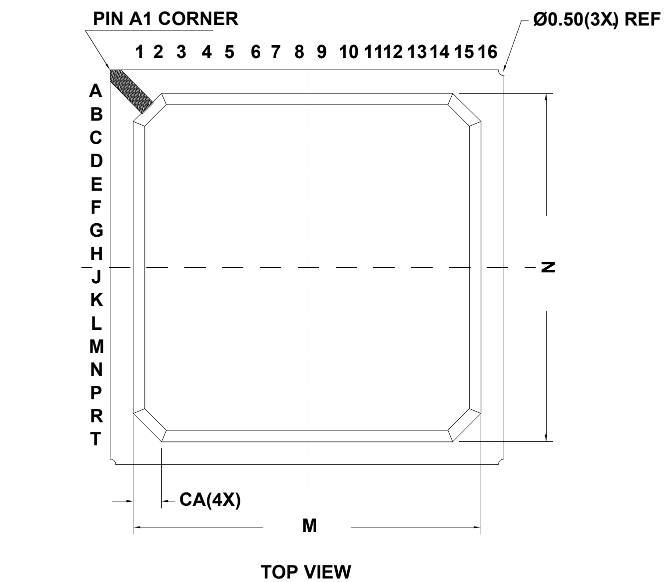
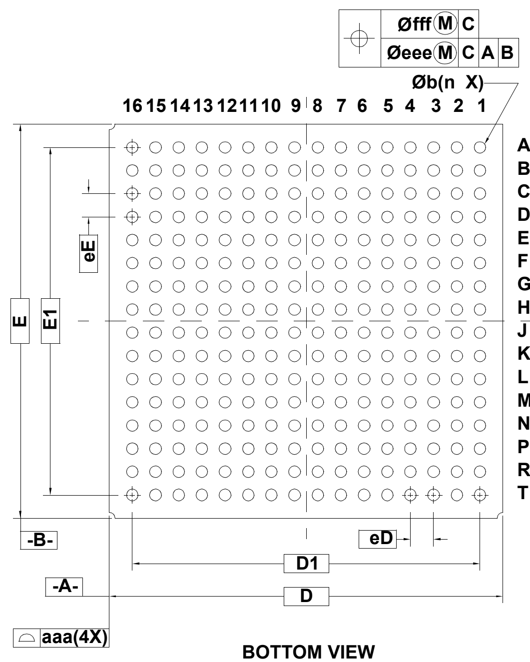
Package Outline Drawing

V256.17x17B

256 LOW PROFILE PLASTIC BALL GRID ARRAY PACKAGE (LBGA)

Rev 0, 1/12





		SYMBOL	COMMON DIEMENSIONS
Package			LBGA
Body Size	X	D	17.00
	Y	E	17.00
Ball Pitch	X	eD	1.000
	Y	eE	1.000
Total Thickness		A	1.810 ±0.190
Mold Thickness		A3	0.850 Ref.
Substrate Thickness		A2	0.560 Ref.
Ball Diameter			0.500
Stand Off		A1	0.300 ~ 0.500
Ball Width		b	0.400 ~ 0.600
Mold Area	X	M	15.000
	Y	N	15.000
Chamfer		CA	1.200 Ref.
Package Edge Tolerance		aaa	0.200
Substrate Flatness		bbb	0.250
Mold Flatness		ccc	0.350
Coplanarity		ddd	0.200
Ball Offset (Package)		eee	0.250
Ball Offset (Ball)		fff	0.100
Ball Count		n	256
Edge Ball Center to Center	X	D1	15.000
	Y	E1	15.000